



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: Not Yet Assigned

Confirmation No.: Not Yet Assigned

Examiner: Not Yet Assigned

Filed: November 25, 2003

For: HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF
MANUFACTURING THE PACKAGE

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §§ 1.97 and 1.98

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicants hereby
notify the U.S. Patent and Trademark Office of the documents which are listed on the attached
PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem
material to patentability of the claims of the above-identified application.

<u>Serial No.</u>	<u>Applicant's Name</u>	<u>Filing Date</u>
10/721,384	Hien Boon TAN et al.	November 26, 2003

One copy of each of the listed documents, other than any U.S. patents and patent
publications, is submitted herewith.

The present Information Disclosure Statement is being filed: (1) No later than three
months from the application's filing date; (2) Before the mailing date of the first Office Action

INFORMATION DISCLOSURE STATEMENT

U.S. Appln. No.: 10/721,382

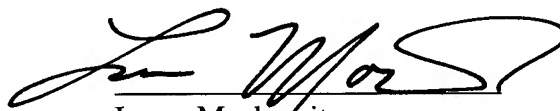
ATTORNEY DOCKET NO. Q78432

on the merits (whichever is later); or (3) Before the mailing date of the first Office Action after filing a request for continued examination (RCE) under §1.114, and therefore, no Statement under 37 C.F.R. § 1.97(e) or fee under 37 C.F.R. § 1.17(p) is required.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicants do not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this paper is attached.

Respectfully submitted,



Laura Moskowitz

Registration No. P-55,470

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: February 25, 2004

INFORMATION DISCLOSURE **STATEMENT BY APPLICANT**

Sheet	1	of	1
-------	---	----	---

Complete if Known

Application Number	10/721,382
Confirmation Number	Not Yet Assigned
Filing Date	November 25, 2003
First Named Inventor	Hien Boon TAN
Art Unit	Not Yet Assigned
Examiner Name	Not Yet Assigned
Attorney Docket Number	Q78432

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ² (if known)		
		US 5,363,279	A	11-18-1994	CHA
		US 5,428,248	A	06-27-1995	CHA
		US 6,433,277	B1	08-13-2002	GLENN
		US 6,630,371	B2	10-17-2003	HEMBREE
		US 6,444,498	B1	09-03-2002	HUANG et al.
		US 6,177,718	B1	01-23-2001	KOZONO
		US 5,894,108	A	08-13-1999	MOSTAFAZADEH et al.
		US 5,519,251	A	05-21-1996	SATO et al.
		US 5,770,888	A	06-21-1998	SONG et al.
		US 6,166,430	A	12-26-2000	YAMAGUCHI
		US 5,789,280	A	08-04-1998	YOKOTA

[illegible]

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation ⁶
		<i>Internet Article:</i> Jim Lipman, "NEW IC Packages really pack in the leads", <u>EDN Access</u> , September 1, 1997	
		<i>Internet Article:</i> Ultra BGA, "Circuitize the Heatsink", <u>Substrate Technologies, Inc. - Ultra Technology Family</u>	

Date Considered

¹ Applicant's unique citation designation number (optional). ² See Kind Codes of USPTO Patent Documents at www.uspto.gov, MPEP 901.04 or in the comment box of this document. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to indicate here if English language Translation is attached.